

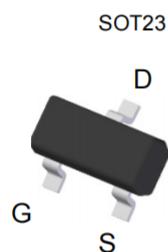
Product Summary

BV _{DSS}	20V
R _{DS(ON)}	250mΩ
I _D	1.2A

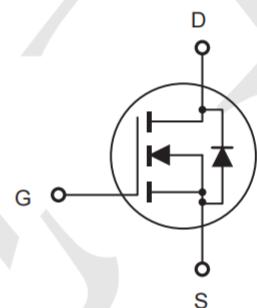
Application

- * Load/Power switch
- * Interfacing, logic switching
- * Battery management for ultra portable electronics

Package and Pin Configuration



Circuit diagram



Marking: A4xx Or AETPM

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“TPM”IS TECHPUBLIC MOSFET
“xx”is internal code

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

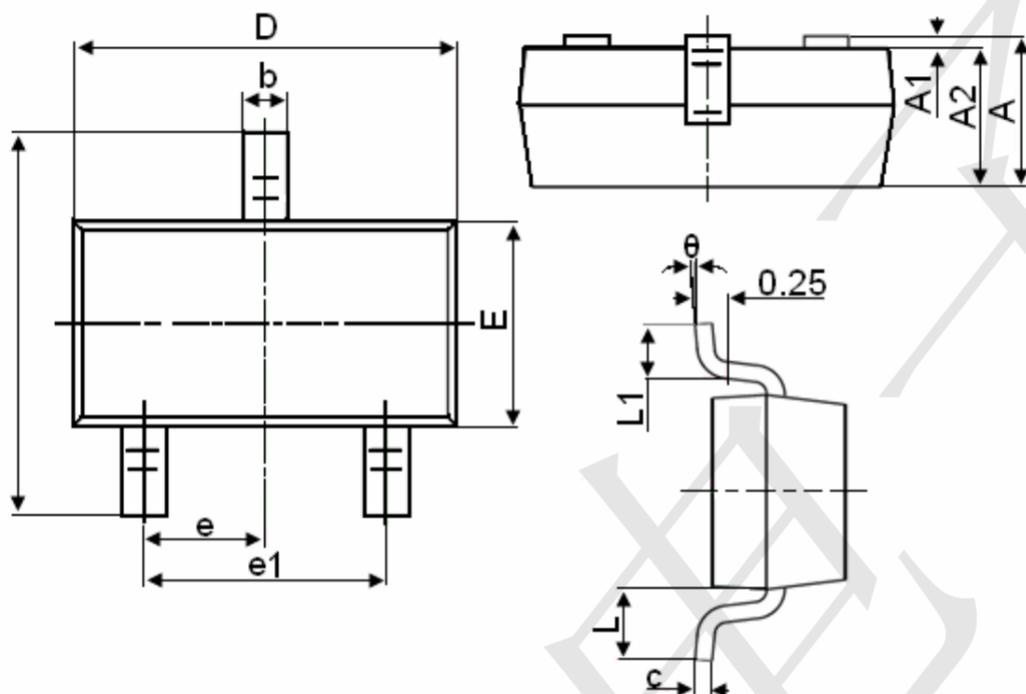
Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current-Continuous	I _D	1.2	A
Drain Current-Pulsed ¹	I _{DM}	5	A
Maximum Power Dissipation	P _D	540	mW
Thermal Resistance, Junction-to-Ambient ²	R _{θJA}	150	°C/W
Storage Temperature Range	T _{STG}	-55 To +150	°C
Operating Junction Temperature Range	T _J	-55 To +150	°C

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	20		-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=20\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 12\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics³						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	0.7			V
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=1.2\text{A}$	-		250	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=1\text{A}$	-		360	
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=2.9\text{A}$	-	8	-	S
Dynamic Characteristics⁴						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=10\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1\text{MHz}$	-	-	300	pF
Output Capacitance	C_{oss}		-	-	90	
Reverse Transfer Capacitance	C_{rss}		-	-	80	
Switching Characteristics⁴						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=10\text{V}, \text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=2.9\text{A}, \text{R}_{\text{GEN}}=6\Omega$	-	-	15	nS
Turn-On Rise Time	t_r		-	-	85	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	-	45	
Turn-Off Fall Time	t_f		-	-	20	
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=2.9\text{A}, \text{V}_{\text{GS}}=4.5\text{V}$	-	4	10	nC
Gate-Source Charge	Q_{gs}		-	0.65	-	
Gate-Drain Charge	Q_{gd}		-	1.2	-	
Drain-Source Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=2.9\text{A}$	-	0.75	1.2	V
Continuous Source Current ²	I_S		-	-	1.2	A



Package Outline Dimensions (SOT-23)



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

Notes

- All dimensions are in millimeters.
- Tolerance $\pm 0.10\text{mm}$ (4 mil) unless otherwise specified
- Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.